





IP Integratio	MEDEA			
IP Duality	IP Creator	Socket	IP Integrator	
Reuse Style	Ad-hoc Block by Block	Planned Block by Block	SoC Platform	
Design Style	Single-pass ASIC, ASSP or Custom	Block Based Design	Platform Based Design	
Level	Soft	Firm	Hard	
Issues	Control	Time and Space	Economics	
AMS	None	AMS Dominant: A/d	Digital Dominant: D/a	

























 In SOC, Reuse is of <u>Collections of IP blocks</u> organised into HW-SW architectures: also known as <u>Integration Platforms</u>

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THE PLATFORM DESIGN CHAIN The platform creator and user can be different depending on the composition of the platform								
Platform Creator	Platform User	IP Creator owns platform						
ARM PrimeXsys (general purpose)	Sanyo, STMicroelectronics,	Platform User is IDM & System						
TI OMAP (portable multimedia)	Acer, Ericsson, Nokia, Sony, TI, Handspring	-						
Philips Nexperia (multimedia)	Philips Electronics, Acer	IDM owns platform						
Infineon Wireless	eAnywhere	themselves & System						
Motorola Wireless i.250	RTX Telecom, Solomon Group, Giga Telecom, Benq, Eastcom, Compal Communication							
Intel Xscale (general purpose)	Philips Electronics, Viewsonic Corporation, Microsoft PocketPC	IDM owns platform						
Xilinx Vertex II	unknown							



















































VSIA A	MS	Ext	ensions				MEDEA+
	Section		Deliverable	Currently Used Formats	VSI Format(s)	Hard	Comments
	2.6	Physi	cal Block Implementation				
	2.6.1*	Block	description	GDSII, LEF	GDSII	М	
VSI Arch	2.6.2*	Pin lis	t/placement	LEF	VC LEF	М	Required if Hard is netlist based
&	2.6.3*	Porosi	ty/blockage file	LEF	VC LEF	М	
<b>T</b> / <b>T</b> /	2.6.4*	Footpr	int	LEF	VC LEF	М	
I/ V	2.6.5*	Power	/ground	LEF/document	VC LEF	М	
	2.6.7*	Physic	al Netlist	Spice3 netlist format, Verilog-A	VC Hspice	СМ	
				Emerging: VHDL- AMS			
	Sec	tion	Deliverable	Commonly	VSI Format(s)	Hard	Comments
Extend	2.6.A22		Interconnect Specifications	obcu i ormato			
for AMS	2.6.A22	.1	Special Hookup Guidelines	document	document	М	
IUP AND	2.6.A22	.2	Routing Constraints	document	document	М	
	2.6.A22	.3	Special Pin Requirements	document	document	М	
	2.6.A22	.4	Additional Power, Ground, and Substrate Interconnect Constrain	document ts	document	М	





